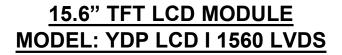
PRODUCT SPECIFICATION





- < >> Preliminary Specification
- < ◆> Finally Specification

CUSTOMER'S APPROVAL							
CUSTOMER:	CUSTOMER:						
SIG	NATURE:	DATE:					

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
-	TFT W. S. L 20241224	TFT 周福云 20241224	TFT L. L 20241224

knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2024.12.24	LL	Initial Release	

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	15.6"	
Display Mode	Transmissive /Normally black	
Resolution	1920 RGB x 1080	Pixels
View Direction	FULL View	Best Image
Module Outline	359.4 (H) x 211.7 (V) x 6.18(T) (Note1)	mm
Active Area	344.16(H) x 193.59(V)	mm
Pixel Pitch	179.25(H) x 179.25(V)	um
Pixel Arrangement	RGB stripe	
Polarizer Surface Treatment	Anti-Glare	
Display Colors	16.7M	
Interface	LVDS interface	
With or without the touch panel	Without	
Operating Temperature	-20~+70	°C
Storage Temperature	-30~+80	°C
Weight	TBD	g

Note 1: Inclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

H_GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Power Supply Voltage	LCD_VCC	-0.3	4.0	V
Storage temperature	T _{STG}	-30	80	°C
Operating temperature	T _{OP}	-20	70	°C

Notes:

- 1. Permanent damage to the device may occur if maximum values are exceeded functional operation should be restricted to the condition described under normal operating conditions.
- 2. Temperature and relative humidity range are shown in the figure below. 90 % RH Max. (40° C \geqslant Ta) Maximum wet bulb temperature at 39° C or less. (Ta > 40° C) No condensation.

4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	NOTE
Supply Voltage	LCD_VCC	3.0	3.3	3.4	V	
Current Consumption All white	Logic Analog	Icc	-	TBD	-	mA

5. Backlight Characteristic

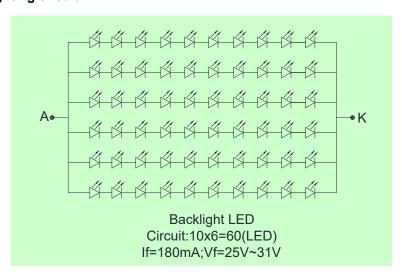
5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I _F =30.0mA/LED	25.0	28.0	31.0	V
Forward Current	lF	Ta=25 °C, VF=2.8V/LED	-	180	-	mA
Power dissipation	Po	-	-	5040	-	mW
Uniformity	Avg	-	-	80	-	%
LED working life(25℃)	-		-	30000	-	Hrs
Drive method	Constant current					
LED Configuration	60 White LEDs (10 LEDs in one string and 6 groups in parallel)					

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25±2 °C,60%RH±5%,I_F=30 mA/LED.

5.2. Backlighting circuit



6. Optical Characteristics

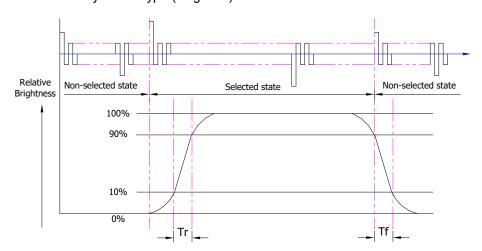
6.1. Optical Characteristics

Ta=25°C, LCD_VCC=3.3V

					S	pecification	nn		
	Iter	m	Symbol	Condition	Min.	Тур.	Max.	Unit	
	Luminance on								
	TFT(I_f =30.	0mA/LED)	Lv		200	250	-	cd/m²	
80	Contrast rati	o(See 6.3)	CR		(1000)	(1500)	-		
sive M	Contrast ratio(See 6.3) Response time (See 6.2) Red Chromaticity Transmissive (See 6.5) Blue White		TR+TF		-	25	35	ms	
nis		Red	XR		-	TBD	-		
nsr		Red	YR		-	TBD	-		
Tra	Chromoticity	hromaticity Green	Xg		-	TBD	-		
<u>ب</u>	Transmissive		YG		-	TBD	-		
) t			Blue	Хв		-	TBD	-	
jij	(000 0.0)	Dide	Yв		-	TBD	-		
ac k		White	Xw		-	TBD	-		
<u> </u>		VVIIILG	Yw		-	TBD	-		
	Viewing Angle (See 6.4)	Horizontal	θx+		80	85	-		
		Tionzontal	θх-	Center	80	85	-	Deg.	
		Vertical	фҮ+	(CR>10)	80	85	-	Deg.	
	(000 0.4)	vertical	φY-		80	85	-		
	NTSC	ratio			65	70	-	%	

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

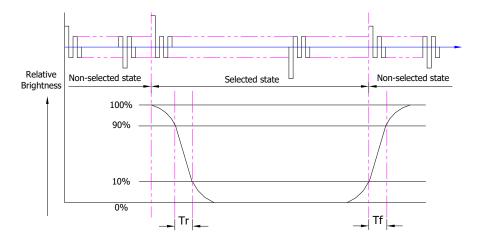


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

6.3. Definition of Contrast Ratio

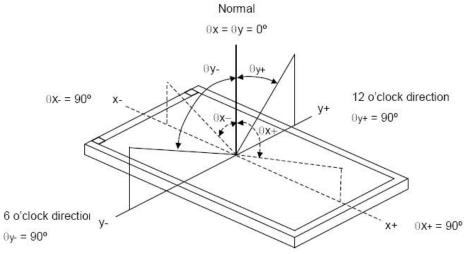
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent	
Measuring Point Diameter	3mm//1mm	
Measuring Point Location	Active Area centre point	
Toot pottorn	A: All Pixels white	
Test pattern	B: All Pixel black	
Contrast setting	Maximum	

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



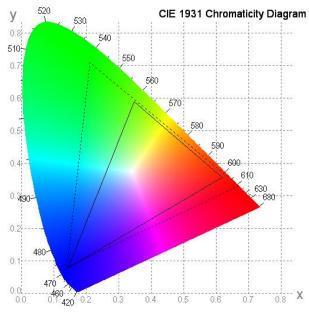
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

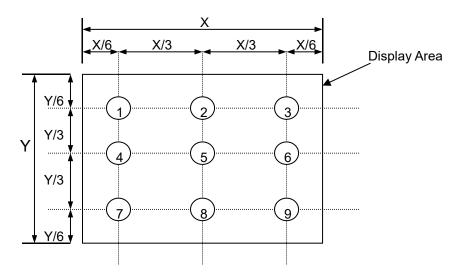


6.6. Definition of Surface Luminance, Uniformity and Transmittance

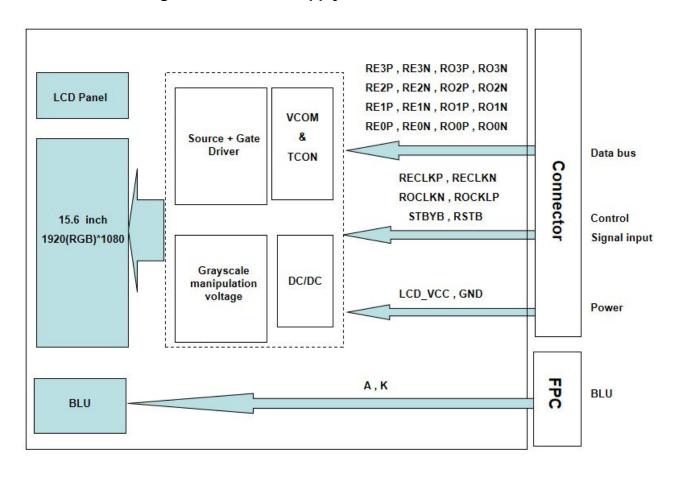
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 6.6.2. Uniformity = Minimal $(L_{P1}:L_{P9})$ / Maximal $(L_{P1}:L_{P9})$ * 100%
- 6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



8. Interface Pins Definition

Connector:LV03040-13100

No.	Symbol	Function	Remark
1	RE3P	Positive LVDS differential data input Channel E3(Even)	
2	RE3N	Negative LVDS differential data input Channel E3(Even)	
3	RECLKP	Positive LVDS differential clock input(Even)	
4	RECLKN	Negative LVDS differential clock input(Even)	
5	RE2P	Positive LVDS differential data input Channel E2(Even)	
6	RE2N	Negative LVDS differential data input Channel E2(Even)	
7	GND	Ground	
8	RE1P	Positive LVDS differential data input Channel E1(Even)	
9	RE1N	Negative LVDS differential data input Channel E1(Even)	
10	RE0P	Positive LVDS differential data input Channel E0(Even)	
11	RE0N	Negative LVDS differential data input Channel E0(Even)	
12	RO3P	Positive LVDS differential data input Channel O3(Odd)	
13	RO3N	Negative LVDS differential data input Channel O3(Odd)	
14	GND	Ground	
15	ROCLKP	Positive LVDS differential clock input(Odd)	
16	ROCKLN	Negative LVDS differential clock input(Odd)	
17	GND	Ground	
18	RO2P	Positive LVDS differential data input Channel O2(Odd)	
19	RO2N	Negative LVDS differential data input Channel O2(Odd)	
20	RO1P	Positive LVDS differential data input Channel O1(Odd)	
21	RO1N	Negative LVDS differential data input Channel O1(Odd)	
22	RO0P	Positive LVDS differential data input Channel O0(Odd)	
23	RO0N	Negative LVDS differential data input Channel O0(Odd)	
24	GND	Ground	
25	NC	No connection	
26	NC	No connection	
27	NC	No connection	
28	LCD_VCC	LCD Power 3.3V	
29	LCD_VCC	LCD Power 3.3V	
30	LCD_VCC	LCD Power 3.3V	
31	LED_PWM	No connection	
32	LED_EN	No connection	
33	GND	Ground	
34	STBYB	Deep standby mode setting pin	
35	RSTB	Device Reset for LCD driver IC, Low active	
36	GND	Ground	
37	BL_POWER	No connection	
38	BL_POWER	No connection	
39	BL_POWER	No connection	
40	BL_POWER	No connection	

BLU:

No.	Symbol	Function	Remark
1	A	Backlight Anode.	
2	А	Backlight Anode.	
3	А	Backlight Anode.	
4	А	Backlight Anode.	
5	NC	No connection	
6	NC	No connection	
7	К	Backlight Cathode.	
8	К	Backlight Cathode.	
9	К	Backlight Cathode.	
10	К	Backlight Cathode.	

9. AC Characteristics

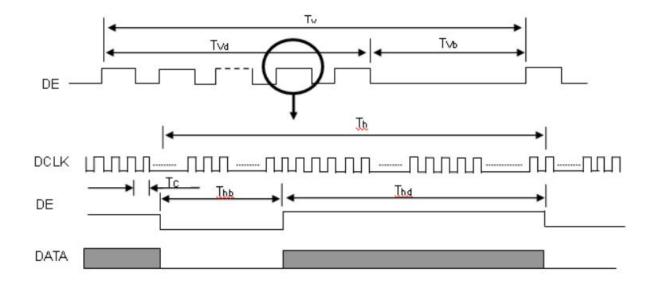
9.1. DISPLAY TIMING SPECIFICATIONS

The input signal timing specifications are shown as the following table and timing diagram.

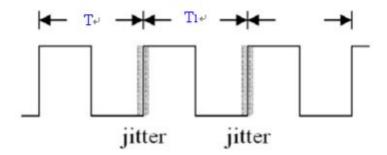
Signal	Item	Symbol	Min.	Тур.	Max.	Unit	Note	
LVDS Clock	Frequency	Fc	60	72	87.5	MHz	-	
	Period	Tc	-	13.89	1141	ns		
	Input cycle to cycle jitter	T _{rcl}	-	=	200	ns	(1)	
	Spread spectrum modulation range	Fclkin_ mod	Fc*98%	=	Fc*102%	MHz	(2)	
	Spread spectrum modulation frequency	Fssm	-	5	200	KHz	(2)	
	Frame Rate	Fr	50	60	75	Hz	-	
0.0	Total	Tv	1090	1100	1160	T _{H_TOTA}	Tv=Tvd+Tvb	
Vertical Display Term	Active Display	Tvd	-	1080	-	T _{H_TOTA}	٤	
	Blank	Tvb	10	20	80	T _{H_TOTA}	-	
Horizontal Display Term	Total	Th	1000	1088	1120	DClk	Th=Thd+Thb	
	Active Display	Thd	1	960	-	DClk	-	
	Blank	Thb	40	128	160	DClk	-	

Note: Because this module is operated by DE only mode, Hsync and Vsync input signals are ignored.

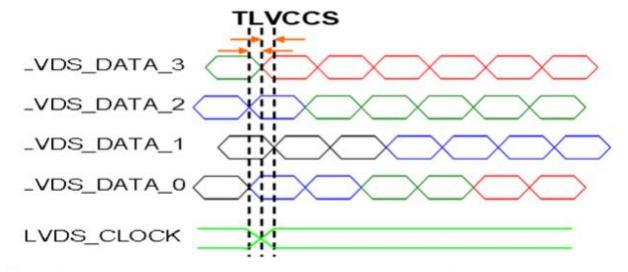
9.2. INPUT SIGNAL TIMING DIAGRAM



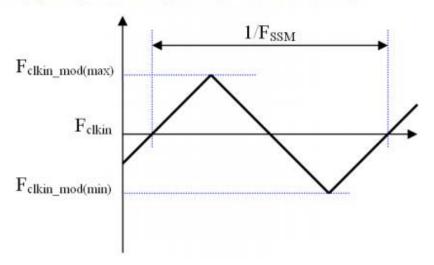
Note (1) The input clock cycle-to-cycle jitter is defined as below figures. Trcl = I T₁ - TI



Note (2) Input Clock to data skew is defined as below figures.

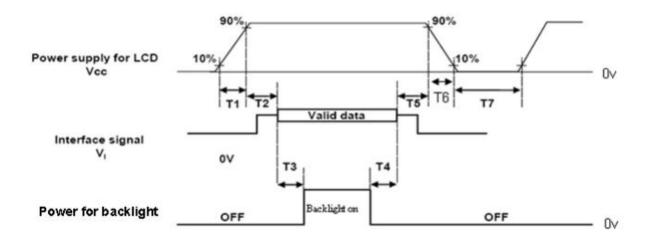


Note (3) The SSCG (Spread spectrum clock generator) is defined as below figures.



9.3. POWER SEQUENCE

The power sequence specifications are shown as the following table and diagram.



Timing Specifications:

December		Helle			
Parameters -	Min	Тур.	Max	Units	
T1	0.1	(5)	10	ms	
T2	0	30	50	ms	
Т3	200	250	-	ms	
T4	100	250	-	ms	
T5	0	20	50	ms	
T6	0.1	-	10	ms	
T7	1000	-	-	ms	

- Note (1) The supply voltage of the external system for the module input should be the same as the definition of Vcc.
- Note (2) When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.
- Note (3) In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.
- Note (4) T4 should be measured after the module has been fully discharged between power off and on period.
- Note (5) Interface signal shall not be kept at high impedance when the power is on.
- Note (6) CMI won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.
- Note (7) There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "t6 spec".

10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3. Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
 - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
 - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
 - 10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
 - 10.3.2.1. Non-conforming product over PPM level will be replaced.
 - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

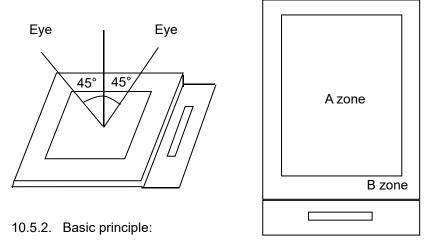
10.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
 - 10.5.1.1. The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.
 - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
 - 10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

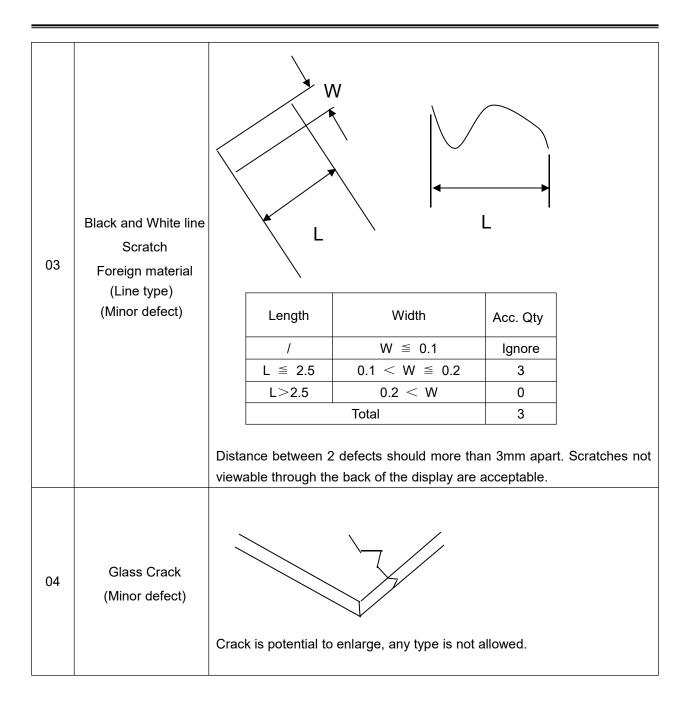


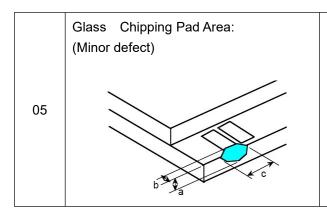
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

10.5.2.2. New item must be added on time when it is necessary.

10.6.Inspection Specification

No.	Item	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	b φ= (a + b) /2 Distance between 2 defects sh	Area Size φ≤0.20 0.20<φ≤0.50 0.50<φ ould more than 5mm a	Acc. Qty Ignore N≤3 0	
02	Electrical Defect (Minor defect)	Dark dot Total dot	N≤2 N≤ N≤4 N≤ N≤4 N≤ Not visible through 5% filters.	Note 2	





Length and Width	Acc. Qty	
c > 3.0, b< 1.0	1	
c< 3.0, b< 1.0	3	
a <glass td="" thickness<=""></glass>		

	Glass Chipping Rear of Pad Area: (Minor defect)			
	(Willion defect)		Length and Width	Acc. Qty
			c > 3.0, b< 1.0	1
06			c< 3.0, b< 1.0	2
			c< 3.0, b< 0.5	4
			a <glass td="" thicl<=""><td></td></glass>	
	by		a Glass IIIIG	(1e33
	Glass Chipping Except Pad Area: (Minor defect)			
	(William delect)		Length and Width	Acc. Qty
			c > 3.0, b< 1.0	1
07			c< 3.0, b< 1.0	2
			c< 3.0, b< 0.5	4
	b		a <glass td="" thicl<=""><td></td></glass>	
	a			
	Glass Corner Chipping:			
	(Minor defect)			
			Length and Width	Acc. Qty
			c < 3.0, b< 3.0	Ignore
80			a <glass td="" thicl<=""><td>kness</td></glass>	kness
	b			
	Glass Burr:			
	(Minor defect)		Length	Acc. Qty
			F < 1.0	Ignore
09	F	Glass	burr don't affect as	

10	FPC Defect: (Minor defect)		(w: circuitry width.) 10.2 Open circuit is	 10.1 Dent, pinhole width a<w 3.<="" li=""> (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion. </w>	
11	Bubble on Polarizer (Minor defect)		Diameter φ≤0.30 0.30 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤2 N=0	
12	Dent on Polarizer (Minor defect)		Diameter φ≤0.25 0.25 <φ≤0.50 0.50 < φ	Acc. Qty Ignore N≤4 None	
13	Bezel	13.1 No rust, distortion on the Bezel.13.2 No visible fingerprints, stains or other contamination.			
14	PCB	14.1 No distortion or contamination on PCB terminals.14.2 All components on PCB must same as documented on the BOM/component layout.14.3 Follow IPC-A-600F.			on the
15	Soldering	Follow IPC-A-610C standard			
16	Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.			

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

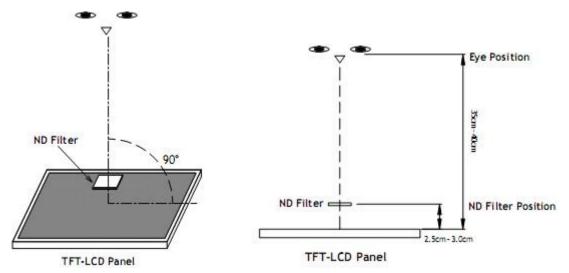
10.8.Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1:Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃,80%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃,96Hrs,	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-30℃, 30min~80℃, 30min, 10 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~500Hz Acceleration of gravity:1.5G X,Y,Z 60 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: \pm 8KV 150pF/330 Ω 5 times	2	GB/T17626.2
	Lieutical Static Discharge	Contact: \pm 4KV 150pF/330 Ω 5 times		-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.7- 2018

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1. Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting

Solder Pin Lead

Recommended

Solder Pin Lead

Not Recommended

12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

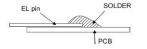
Typical Soldering Time: ≤2s

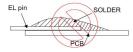
Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting





Recommended

Not Recommended

12.4.2.7. The type of the solder iron:





Recommended

Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7. Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

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TBD

14. Outline Drawing

